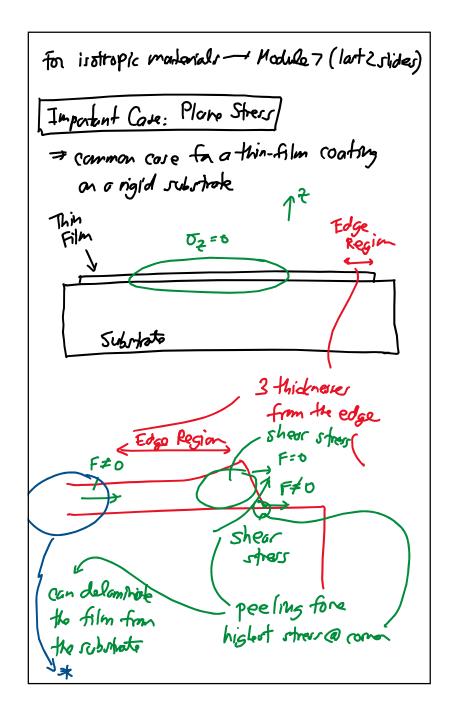
Lecture 11: Mechanics of Materials I

- · Announcements:
- · Module 7 on "Mechanics of Materials" online
- · HW#3 due Tuesday, 3/5, at 9 a.m.
- · Note: The hdmi projector interface was broken
 - Had to spend time setting up the VGA interface
 - ♦ Lost about 15 minutes, which we'll make up in a video lecture the next time I travel
- •
- · Reading: Senturia, Chpt. 8
- · Lecture Topics:
 - \$Stress, strain, etc., for isotropic materials
 - Thin films: thermal stress, residual stress, and stress gradients
 - ♥ Internal dissipation
 - MEMS material properties and performance metrics
- -----
- · Last Time:
- · Started Module 7 on "Mechanics of Materials"
- · Now, continue with this ...

Example. Exercise the "terms" = debruise the Nolume change DV for a unloxial stress (along the x-direction) Upon application of Tx, what is the when change DV? Before Tx - After Tx $\Delta x \longrightarrow \Delta x(1+\epsilon x)$ assuming $\Delta y \longrightarrow \Delta y(1-\nu\epsilon x)$ isotrapic molerial some y dang x fy

The resulting rolume charge: DV = DYDy DZ(1+6x)(1-26x) - DX Aysz volume after applying ox = bxbysz[(1+6x)(1-v6x)2-] [Assume small strains] = (4 mx) = 1+nmx Binemial Thorson ΔV=Δ×Δng Δ7 ((1+6x)(1·2νεx)-1] DV= BXBYDZ(1-22)Ex Fn >= 0.5 (ribber) -> SV=0, no volumo 2105- finites



Lecture 11w: Mechanics of Materials I

Take a closer look @ this region: Oz=0 Get two comparats of stress (& strash) Ex: = [([[- > ([] + 0)] € 1 = [(Jy - 1/((Jx - 0))] Assume: plane shors - isotrapic: ox= oy= o (symmetry in the xy-plane)) Ex= = [0- 70] $= \frac{0}{\left(\frac{E}{E}\right)} \implies \xi_{X} = \frac{\sigma}{E'}$ Where E'= Bioxial Modulus = E

LINEAR Thermal Exponsion

temperature 1 -+ solids expand in volume

Definition. linear thermal expansion coefficient

Linear Thermal
$$\leq \alpha_{+} = \frac{d \in x}{dT}$$
 [Keluhi]

Remorks.

- Day values tend to be in the 10-6 to 16-7
- (2) 10-6K-1 = 1/unhein/K
- 3 In 3D, get a rolung thermal exp. Coefficient: AV: 34+ ST

for lorgon ST, than Of: f(T) Son Modulo 7 stide 18

Fx. The-Film Thermal Stress Thin-Film (XT+) Si Subotrate (XT5=2.PX 10-6K-1) Assumo 1) Substrate is much thicken than the film. 2 The film deposite stress-free @ Td deposition 3 Than, the whole thing eods to room temperature, Tr. Thermal strain of the Substrate: (in one plano dimension) Es: - OLTEST, AT = Td-Tr If the film were not attached to substrate Efities = - KILLY

But the film is attacked to the substrate thickness of substrate > film thickness : restrate cultur! Therefore, the actual strain experienced by the film is that of the substrate: Efrotteday = - OUTS ST Thus: Thermal) Mirmatel = Esimismatel = (XTF XTS) ST Y Note this is bloxish strain (assuming the film deports irotropically on the (substrate) of, mismatel = (E) f, mismatel